

# SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:



**WÜRTH  
ELEKTRONIK**  
MORE THAN  
YOU EXPECT

Processtechnology: B: Pinlamination

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-009my 330x490mm	50201012	<input type="text" value="9"/>	VS	<div>1</div>		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	<input type="text" value="108"/>		<div>2</div>		
B-RaS-FR4-DS-1.194mm-035+035-TG150-HF...	50203145	<input type="text" value="35"/>	L2	<div>3</div>	A00	B00
		<input type="text" value="1124"/>				
		<input type="text" value="35"/>	L3			
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	<input type="text" value="108"/>		<div>4</div>		
A-RS Kupferfolie-009my 330x490mm	50201012	<input type="text" value="9"/>	RS	<div>5</div>		

Thickness after Pressing

B00:  Tol+:  Tol-:  Dmax:  Dmin:

Thickness over all

Tol+:  Tol-:  Dmax:  Dmin:

Demand for customer

Thickness (D):  Tol+:  Tol-:  Dmax:  Dmin:

Measuring point:  nominal:

Version 1.2.20.35

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